



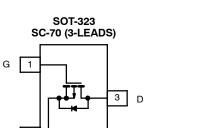
P-Channel 1.8-V (G-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$r_{DS(on)}\left(\Omega\right)$	I _D (A)			
-8	0.280 @ V _{GS} = -4.5 V	-0.92			
	0.380 @ V _{GS} = -2.5 V	-0.79			
	0.530 @ V _{GS} = -1.8 V	-0.67			

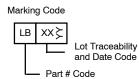
FEATURES

• TrenchFET® Power MOSFET: 1.8 V Rated





Top View



Ordering Information: Si1305DL--T1

Si1305DL--T1-E3 (Lead (Pb)-Free)

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C UNLESS OTHERWISE NOTED)						
Parameter		Symbol	5 secs	Steady State	Unit	
Drain-Source Voltage		V _{DS}	-8		.,	
Gate-Source Voltage		V _{GS}	±8		V	
Continuous Drain Current (T _{.I} = 150°C) ^a	T _A = 25°C	ID	-0.92	-0.86		
Continuous Diam Current (1) = 150 C)	T _A = 70°C	- 'D	-0.74	-0.69	Α	
Pulsed Drain Current		I _{DM}	-3		,,	
Continuous Diode Current (Diode Conduction) ^a		IS	-0.28	-0.24		
Mandanian Danie Director Attack	T _A = 25°C		0.34	0.29	w	
Maximum Power Dissipation ^a	T _A = 70°C	- P _D	0.22	0.19		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to 150		°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
	t ≤ 5 sec	R _{thJA}	315	375	°C/W	
Maximum Junction-to-Ambient ^a	Steady State		360	430		
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	285	340		

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

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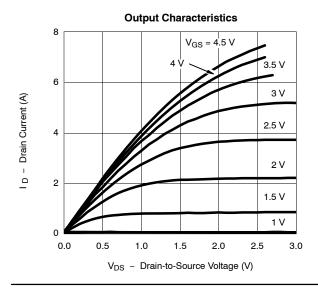
SPECIFICATIONS (T _J = 25°C UNLESS OTHERWISE NOTED)									
Parameter Symbo		Test Condition		Тур	Max	Unit			
Static	<u> </u>								
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \mu A$	-0.45			٧			
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA			
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -8 \text{ V}, V_{GS} = 0 \text{ V}$			-1				
		$V_{DS} = -8 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 70^{\circ}\text{C}$			-5	μΑ			
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	-3			Α			
	r _{DS(on)}	$V_{GS} = -4.5 \text{ V}, I_D = -1 \text{ A}$		0.230	0.280	1			
Drain-Source On-State Resistance ^a		$V_{GS} = -2.5 \text{ V}, I_D = -0.5 \text{ A}$ 0.315		0.315	0.380	Ω			
		$V_{GS} = -1.8 \text{ V}, I_D = -0.3 \text{ A}$		0.440	0.530	1			
Forward Transconductance ^a	9fs	$V_{DS} = -5 \text{ V}, I_{D} = -1 \text{ A}$		3.5		S			
Diode Forward Voltage ^a	V _{SD}	$I_S = -0.3 \text{ A}, V_{GS} = 0 \text{ V}$			-1.2	V			
Dynamic ^b	<u> </u>								
Total Gate Charge	Qg			2.6	4	nC			
Gate-Source Charge	Q _{gs}	V_{DS} = -4 V, V_{GS} = -4.5 V, I_D = -1 A		0.6					
Gate-Drain Charge	Q _{gd}			0.5					
Turn-On Delay Time	t _{d(on)}			8	15				
Rise Time	t _r	$V_{DD} = -4 \text{ V, R}_{L} = 4 \Omega$		55	80	ns			
Turn-Off Delay Time	t _{d(off)}	V_{DD} = -4 V, R_L = 4 Ω I_D \cong -1 A, V_{GEN} = -4.5 V, R_g = 6 Ω		17	25				
Fall Time	t _f			12	20				
Source-Drain Reverse Recovery Time	rce-Drain Reverse Recovery Time t _{rr}			27	45				

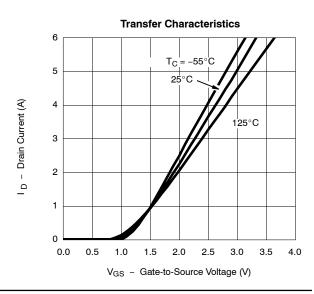
Notes

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2%.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)





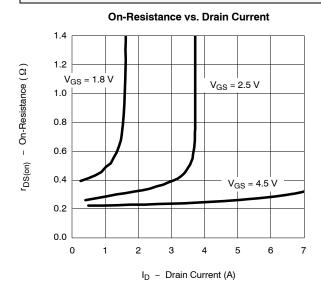




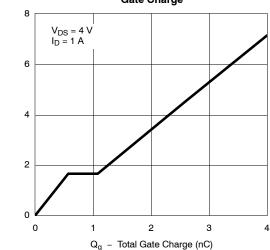
V_{GS} - Gate-to-Source Voltage (V)

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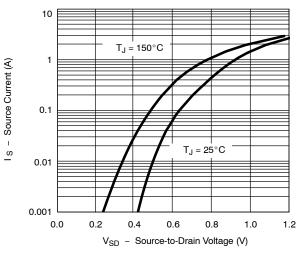
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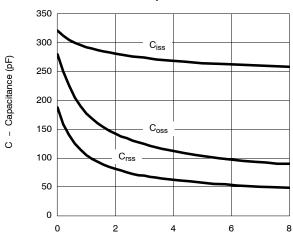




Source-Drain Diode Forward Voltage

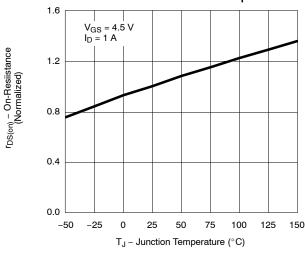


Capacitance

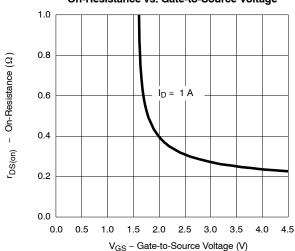


 V_{DS} - Drain-to-Source Voltage (V)

On-Resistance vs. Junction Temperature



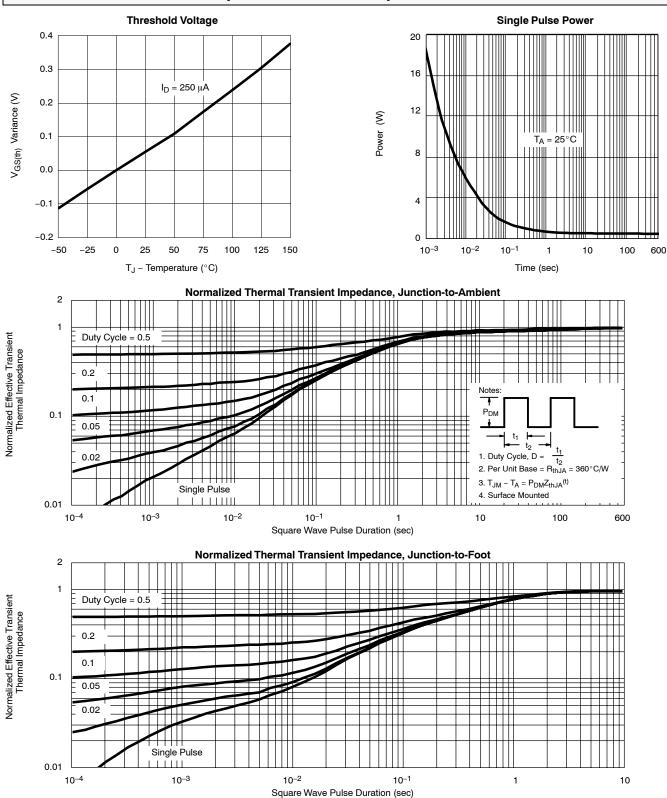
On-Resistance vs. Gate-to-Source Voltage



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TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)



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